

# *Electromechanical characterization of $Nb_3Sn$ conductors at University of Geneva*

*Description on current studies and past experience*

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# Outline



*Carmine Senatore*



***Electromechanical studies – Effects of the transverse stress  
H2020 EuroCirCol WP5 Task 5: Conductor studies***

***@ CERN : Bernardo BORDINI, Davide TOMMASINI***



***Luc GAMPERLE Christian BARTH José FERRADAS***

***Intrinsic mechanisms behind the irreversible  
degradation of the critical current***



***Impact of the voids on the electromechanical  
properties of Nb<sub>3</sub>Sn wires  
Impact of Strand layout and mechanical props.***

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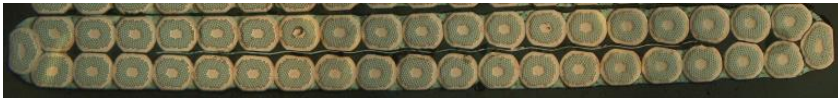
*Impact of the voids on the electromechanical  
properties of Nb<sub>3</sub>Sn wires  
Impact of Strand layout and mechanical props.*



# Degradation upon transverse loads

New high-field  $Nb_3Sn$  magnets are being designed to operate at nominal conditions in a **peak stress range of 150 - 200 MPa**

Are the  $Nb_3Sn$  wires in the cable able to withstand such a high stress level? Which degradation is tolerable?



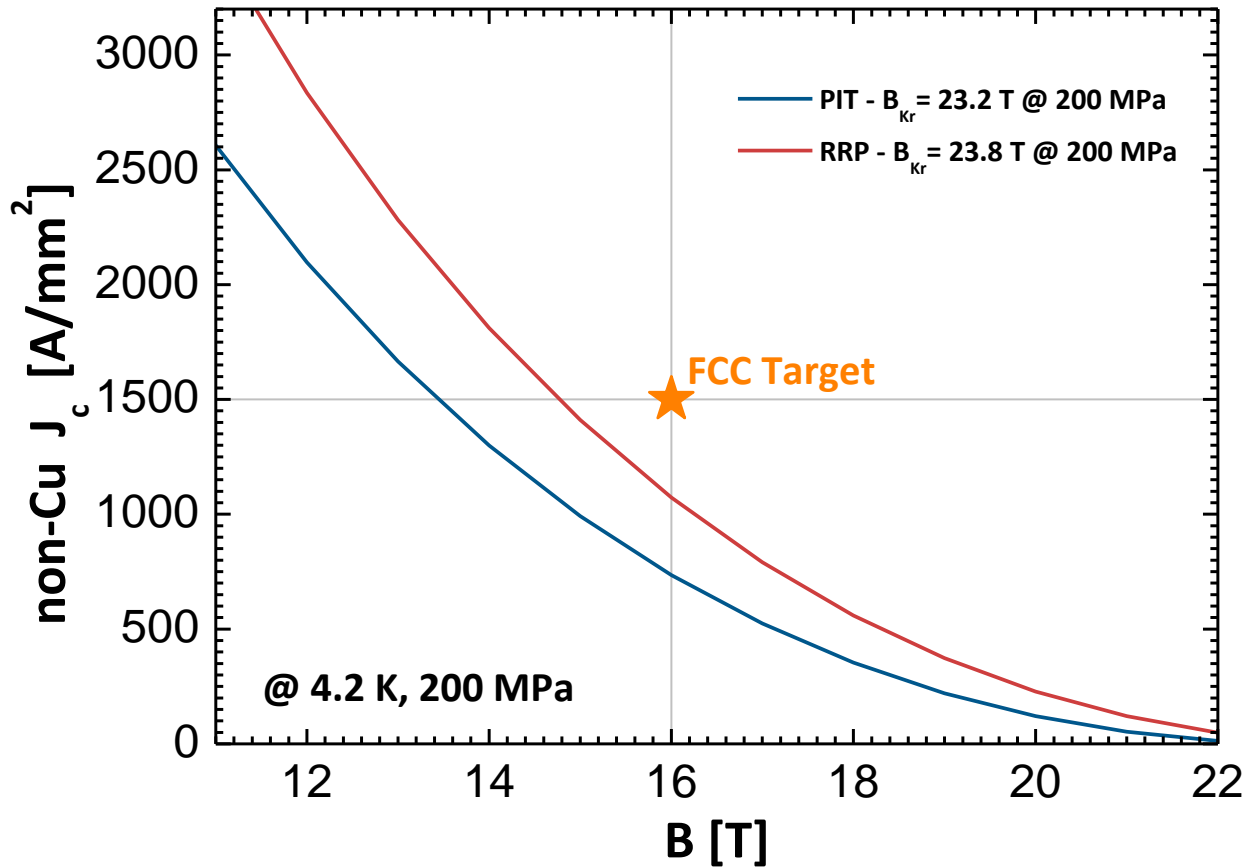
$Nb_3Sn$  Rutherford cable for HL-LHC, 40 strands

- $Nb_3Sn$  wires are deformed during cabling
- Cables are braided with glass fiber
- The winding is impregnated with resin

Is it possible to extrapolate the **behaviour of the cable** from a **single wire experiment**?

# An FCC example:

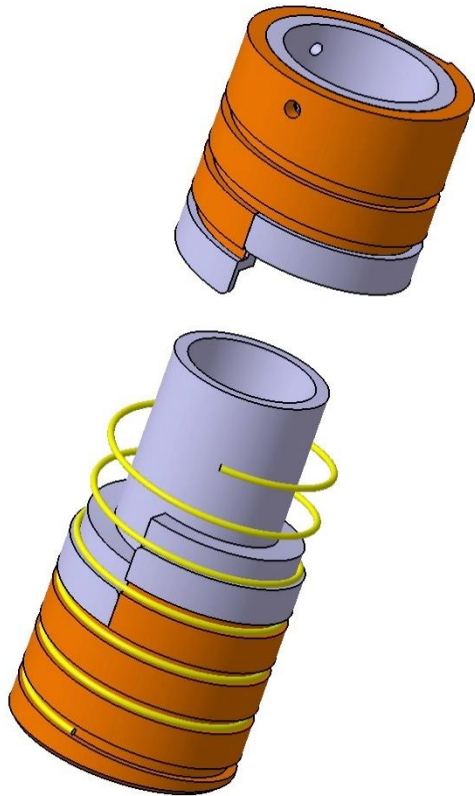
Performance target non-Cu  $J_c(4.2K, 16 T) = 1500 A/mm^2$   
and 200 MPa



*J. Parrell et al., AIP Conf. Proc. 711 (2004) 369*

*T. Boutboul et al., IEEE TASC 19 (2009) 2564*

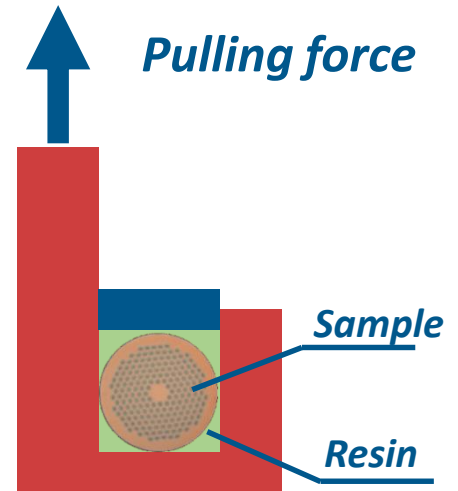
# The WASP concept for $I_c$ vs. transverse stress



3 groove widths —  $1.30\text{ mm}$   
 $1.15\text{ mm}$   
 $1.00\text{ mm}$

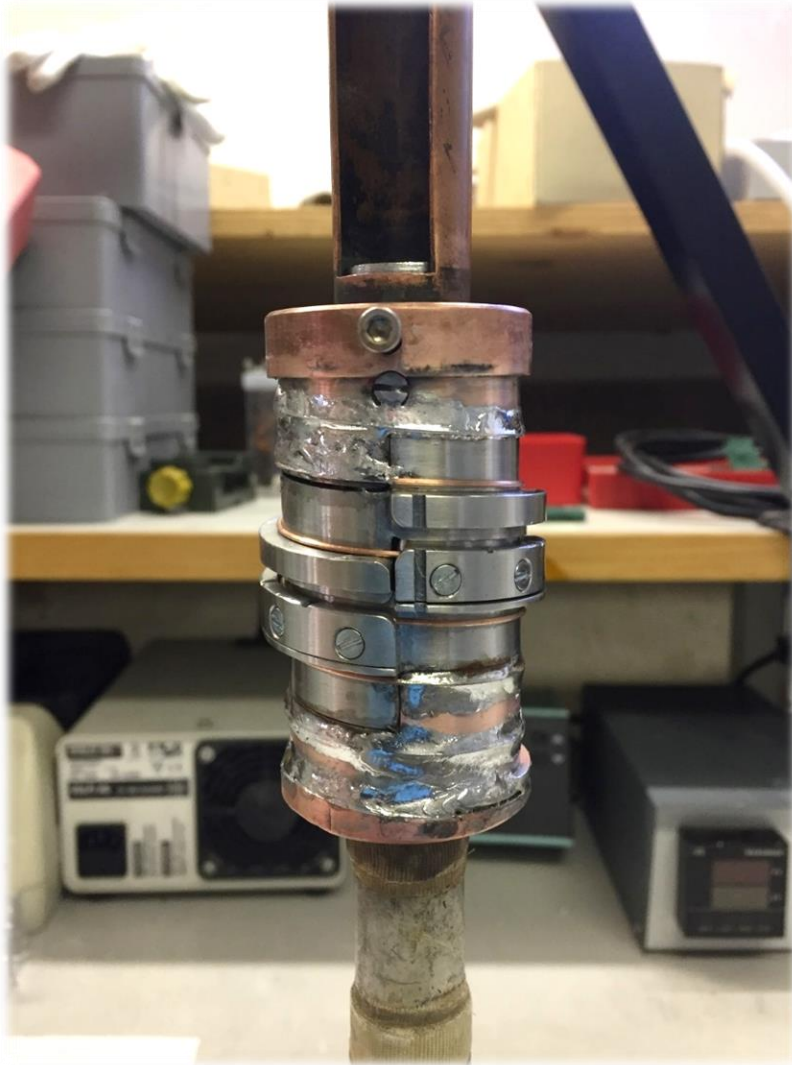
Groove / Gauge length —  $126\text{ mm}$

4-WALL + impregnation





# *The WASP concept for $I_c$ vs. transverse stress*



*How is the wire constrained?*

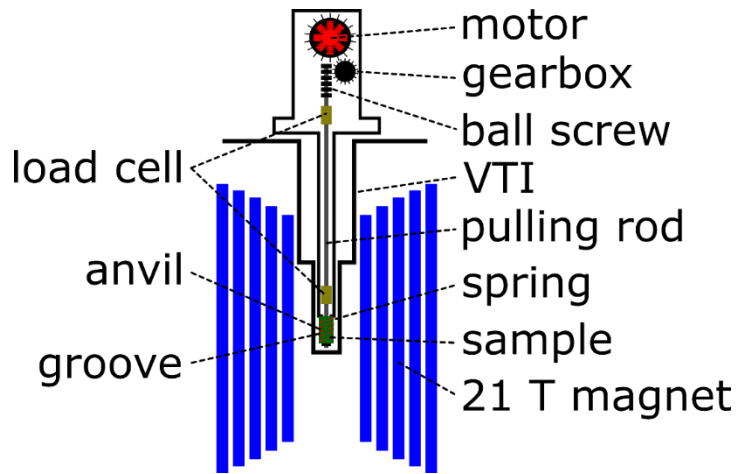
*Strand soldered to the sample holder at both extremities.*

*Wire is free from the exit of the groove to the soldering points (1 turn respectively).*

*The anvil is always in contact with the top epoxy (2 mm height cavity).*

*Voltage taps placed at the entrance / exit of the groove.*

# The WASP concept for $I_c$ vs. transverse stress



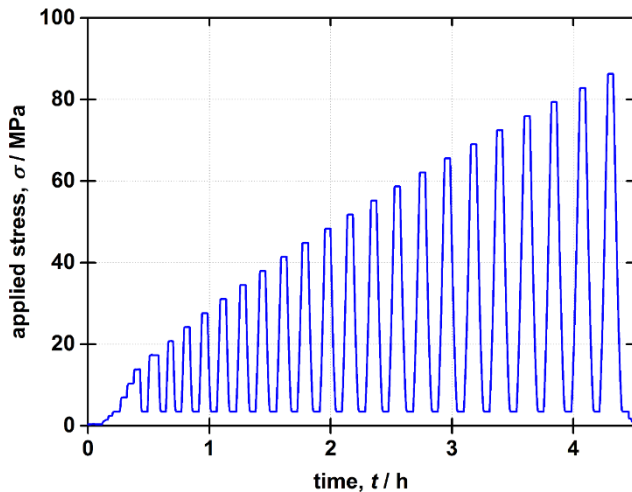
*How are the measurements performed?*

*2 load cells (1x @RT, 1x @4.2 K).*

*PID control loop, |Force deviation| < 20 N.*

*19 T (@4.2 K) measurements.*

*1 kA linear DC power supply.*



*Reference  $I_c$  measurements at 500 N.*

*Incr. force in 500N steps  $\rightarrow I_c$  measurement.*

*Backstep to 500 N  $\rightarrow I_c$  measurement.*

*If  $I_{c,back} < I_{c,ref}$  : Irreversibility reached.*



## *The irreversible limit of the wire under transverse stress is influenced by several parameters*

- *The type of impregnation (the elastic modulus of the resin)*
- *The redistribution of the applied stress on the wire*



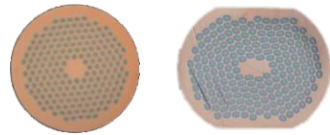
*Rolled wire to simulate the deformation during cabling*



- *The type of wire*

## *PIT and RRP experimental campaigns*

- The PIT experience*



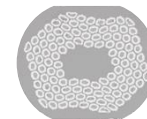
*PIT 192 1mm*

- On-going RRP investigations*

*“FCC”*



*RRP 132/169 1mm*

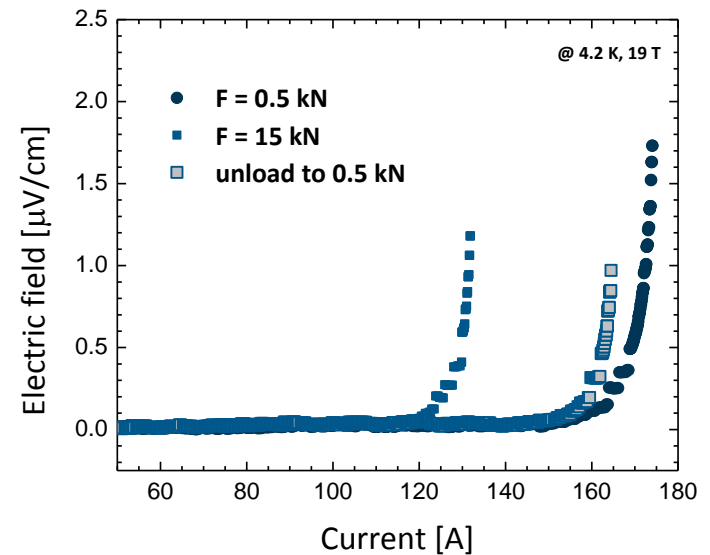
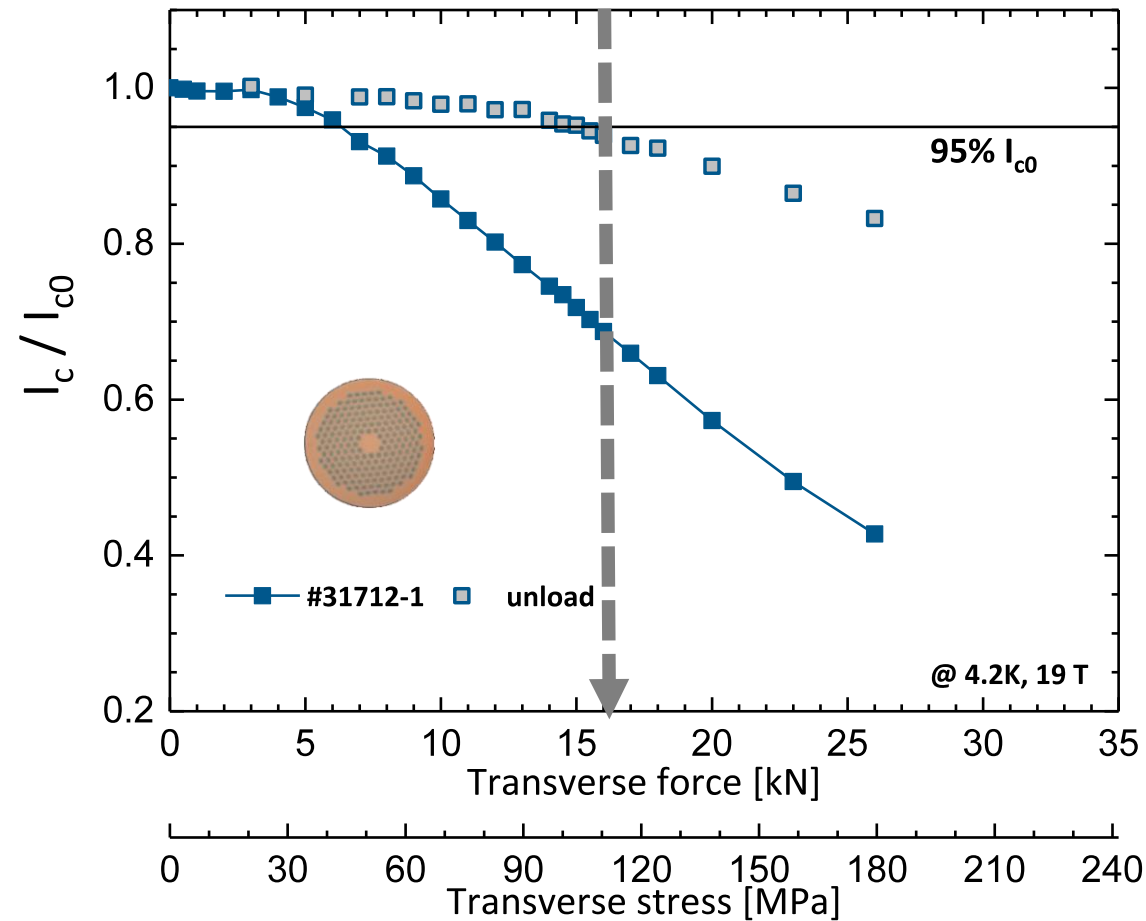


*“HL-LHC”*

*RRP 108/127 0.85mm*

# $I_c$ vs. transverse stress

## PIT 192 + epoxy L



The irreversible limit is defined at the force level leading to a 95% recovery of the initial  $I_c$  after unload

Here

$$F_{irr} = 16 \text{ kN}$$

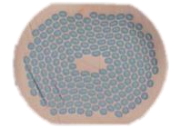
The corresponding irreversible stress limit is

$$\sigma_{irr} = 110 \text{ MPa}$$

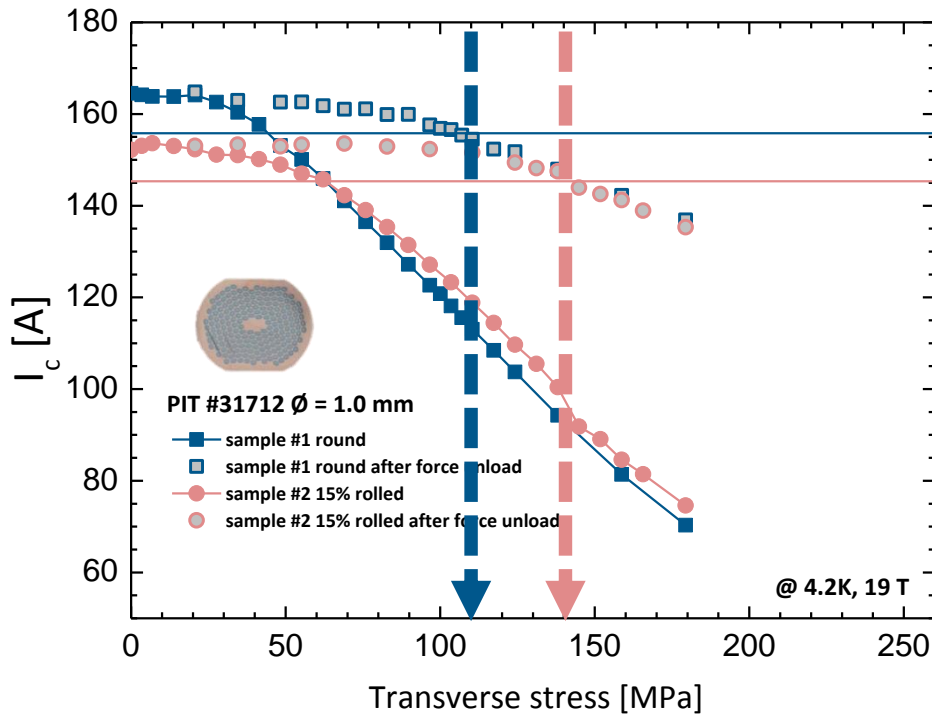
where

$$\text{Stress} = \frac{\text{Force}}{\text{groove length} \times \text{groove width}}$$

# $I_c$ vs. transverse stress on 15% rolled wires



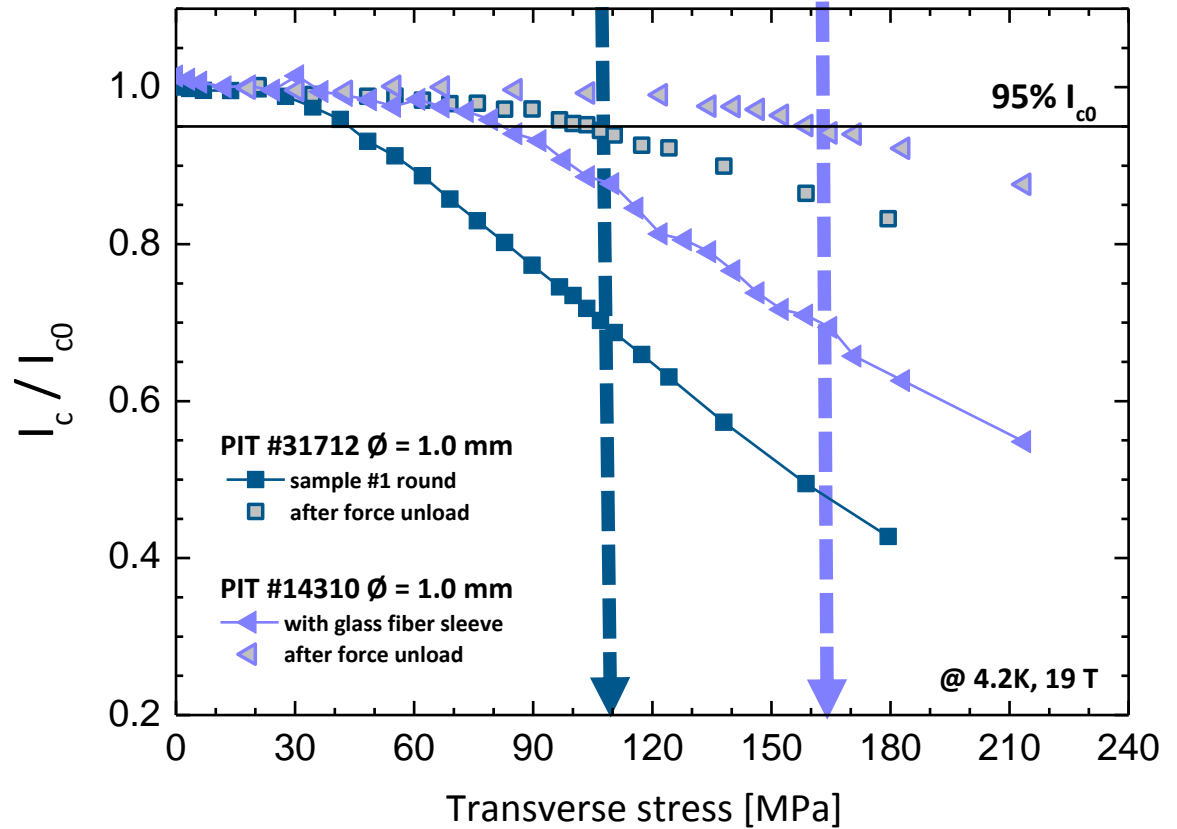
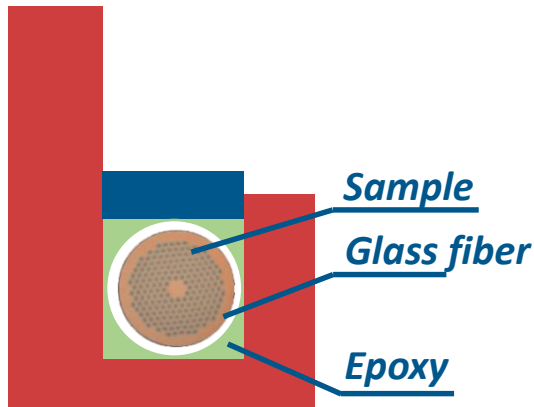
## PIT 192 rolled



*~7.5%  $I_c$  reduction by rolling  
(Degradation due to rolling)*

*Shift of  $\sigma_{irr}$  by ~ 40 MPa*

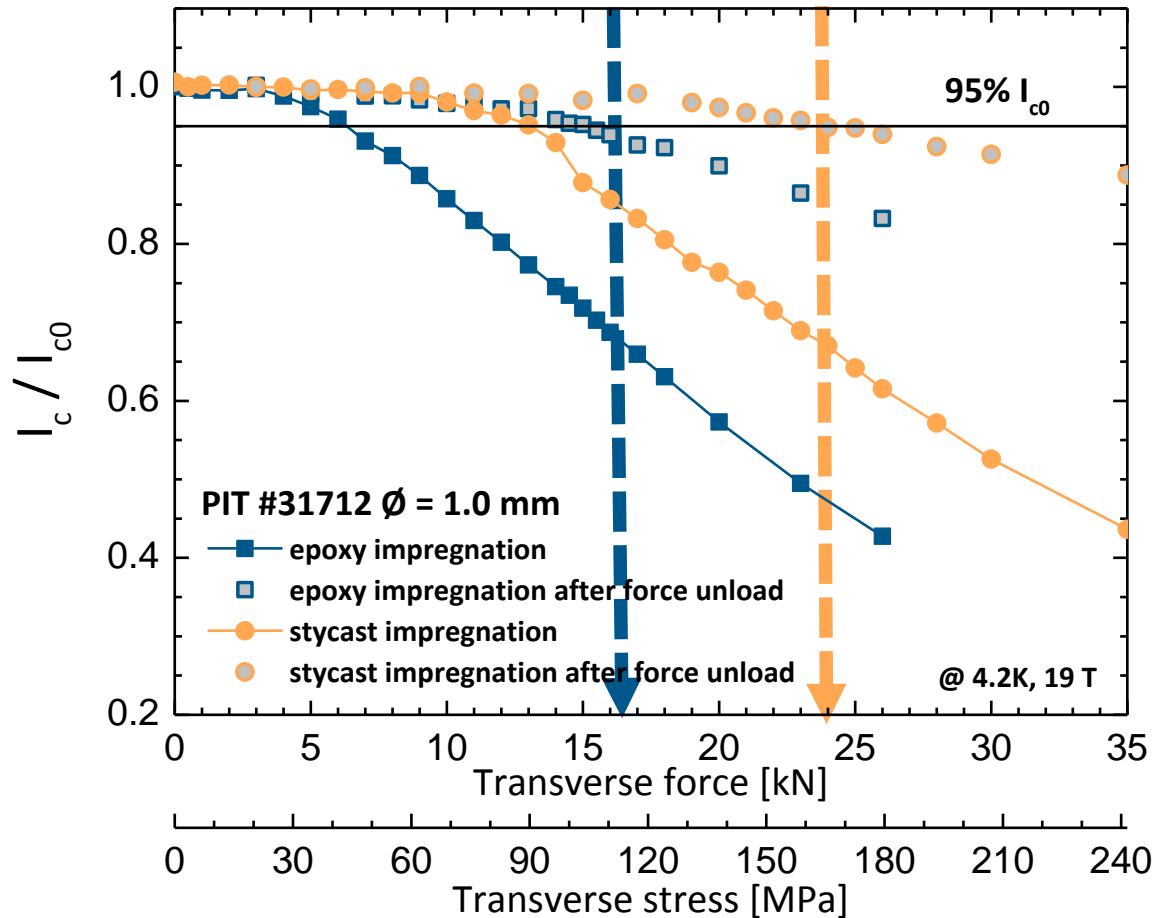
# *$I_c$ vs. transverse stress: wire in a glass fiber sleeve*



*Shift of  $\sigma_{irr}$  by > 50 MPa*

*The wire with glass fiber sleeve was measured in a larger groove (1.30 mm vs 1.15 mm)*

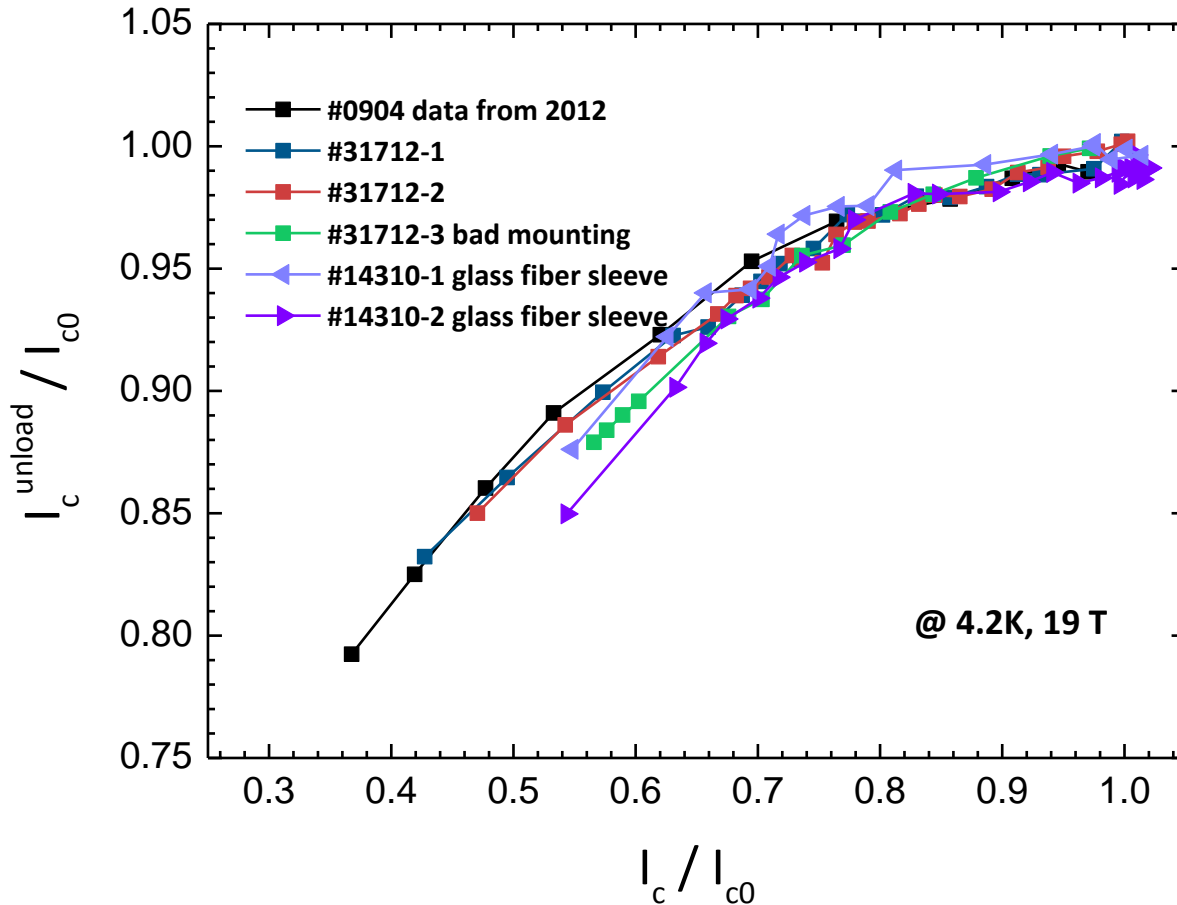
# $I_c$ vs. transverse stress: epoxy L vs. Stycast



*The change of resin, from epoxy to Stycast, leads to an increase of  $\sigma_{irr}$  by > 50 MPa  
The result is comparable to the value found with epoxy + glass fiber sleeve*



# PIT: $I_c / I_{c0}$ vs. $I_c^{unload} / I_{c0}$



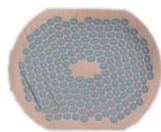
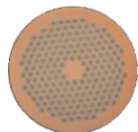
**PIT 192 Round wires**

**X axis:  $I_c / I_{c0}$  Force**  
**Y axis:  $I_c / I_{c0}$  Unloaded**

**Scaling behavior.**  
**Local stress in the filaments.**

## *PIT and RRP experimental campaigns*

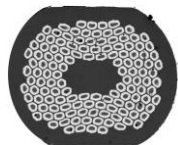
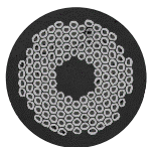
- The PIT experience*



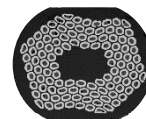
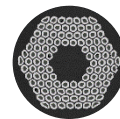
*PIT 192 1mm*

- On-going RRP investigations*

*“FCC”*



*RRP 132/169 1mm*

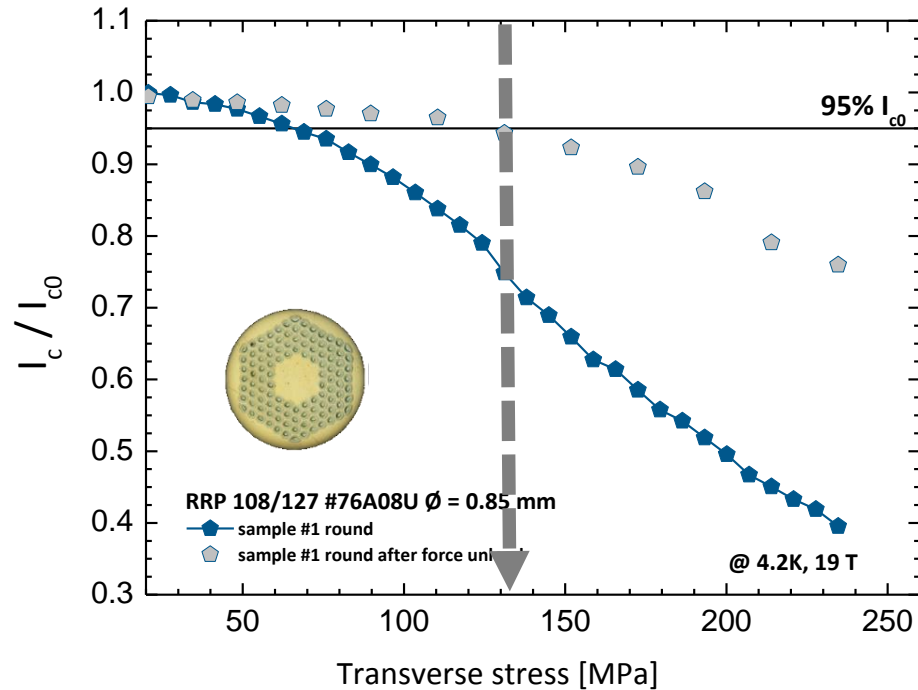


*RRP 108/127 0.85mm*

*“HL-LHC”*

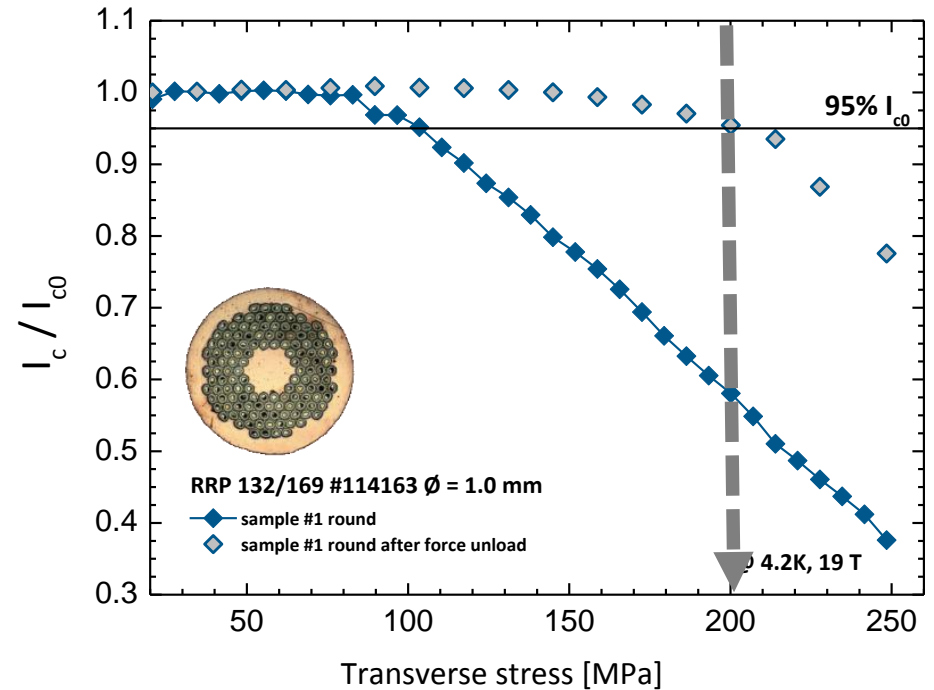
# RRP: 132/169 vs. 108/127

Effect of the wire layout on the irreversible stress limit



**RRP 108/127**

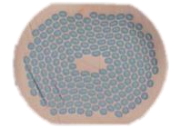
Irreversible stress limit at ~130 MPa



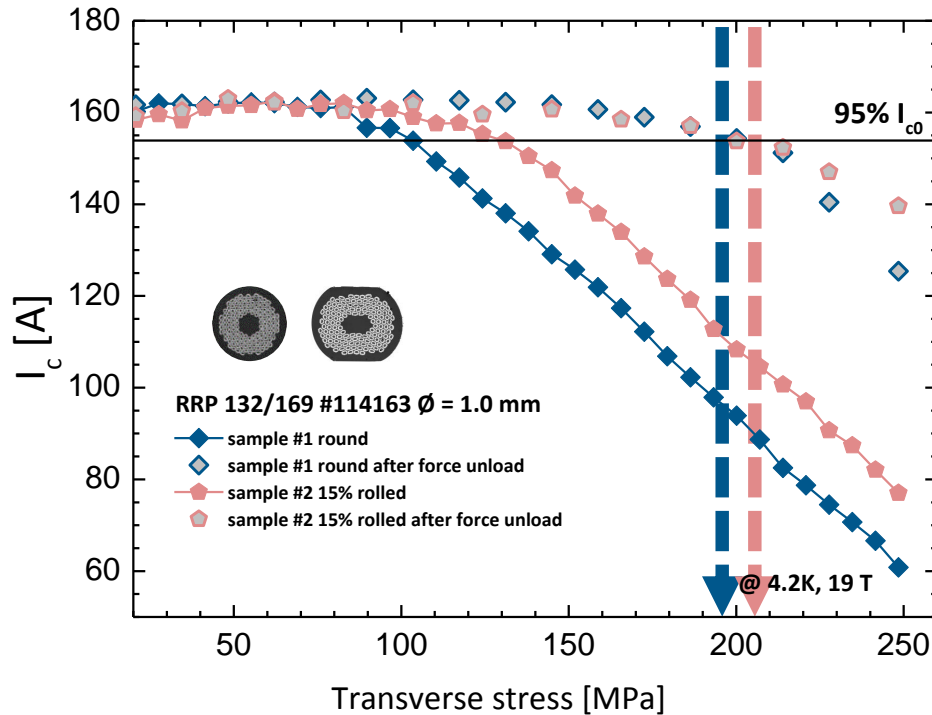
**RRP 132/169**

Irreversible stress limit ~200 MPa

# $I_c$ vs. transverse stress on 15% rolled wires



## RRP 132/169

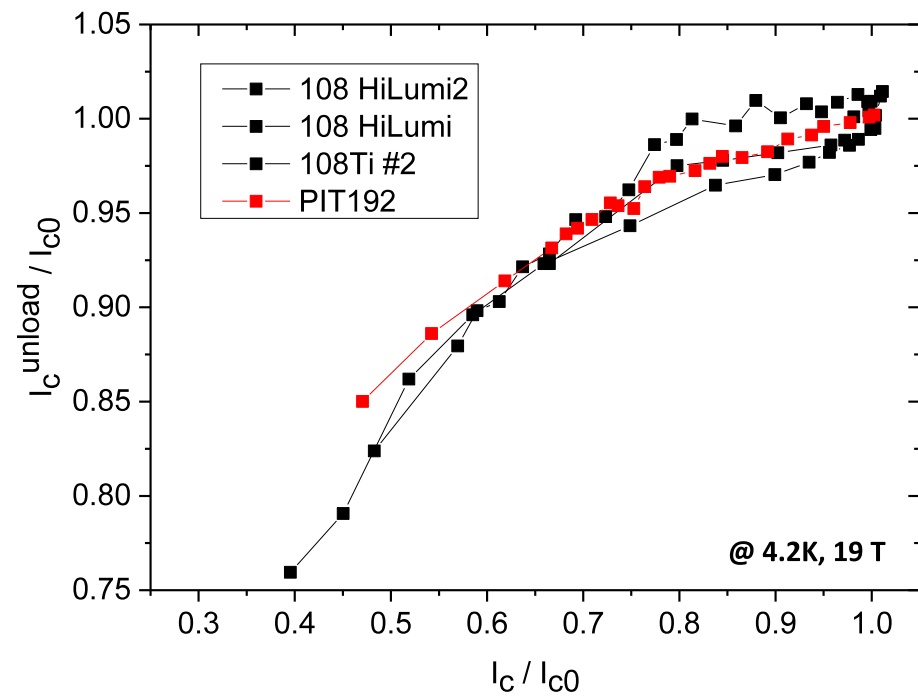


*NO  $I_c$  reduction by rolling*

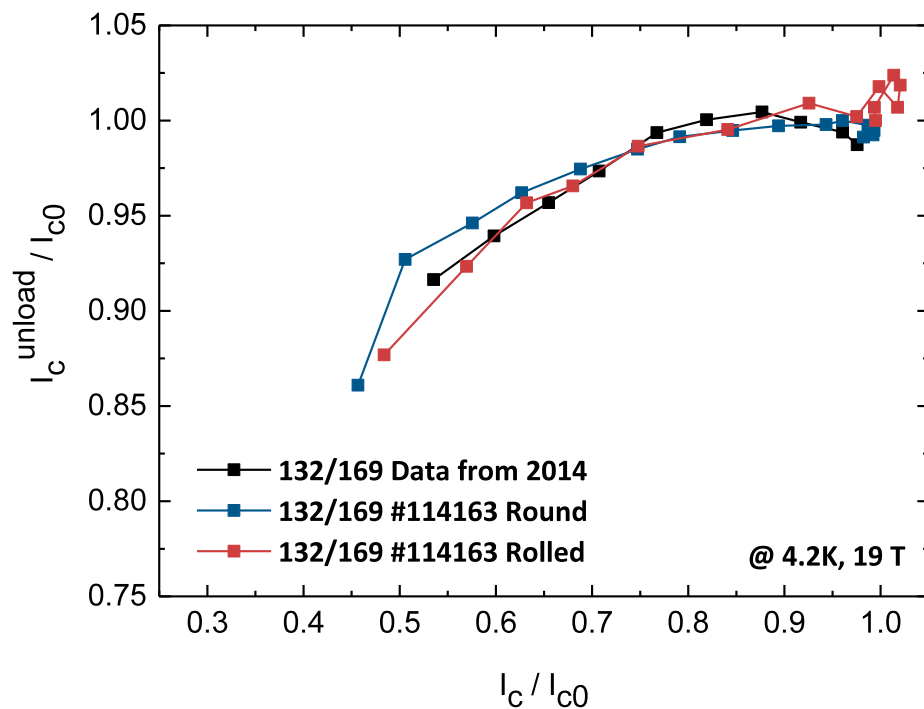
*Shift of  $\sigma_{irr}$  by  $\sim 15$  MPa*

*Measurement on-going for the RRP 108/127 0.85mm strand*

# RRP: $I_c / I_{c0}$ vs. $I_c^{unload} / I_{c0}$

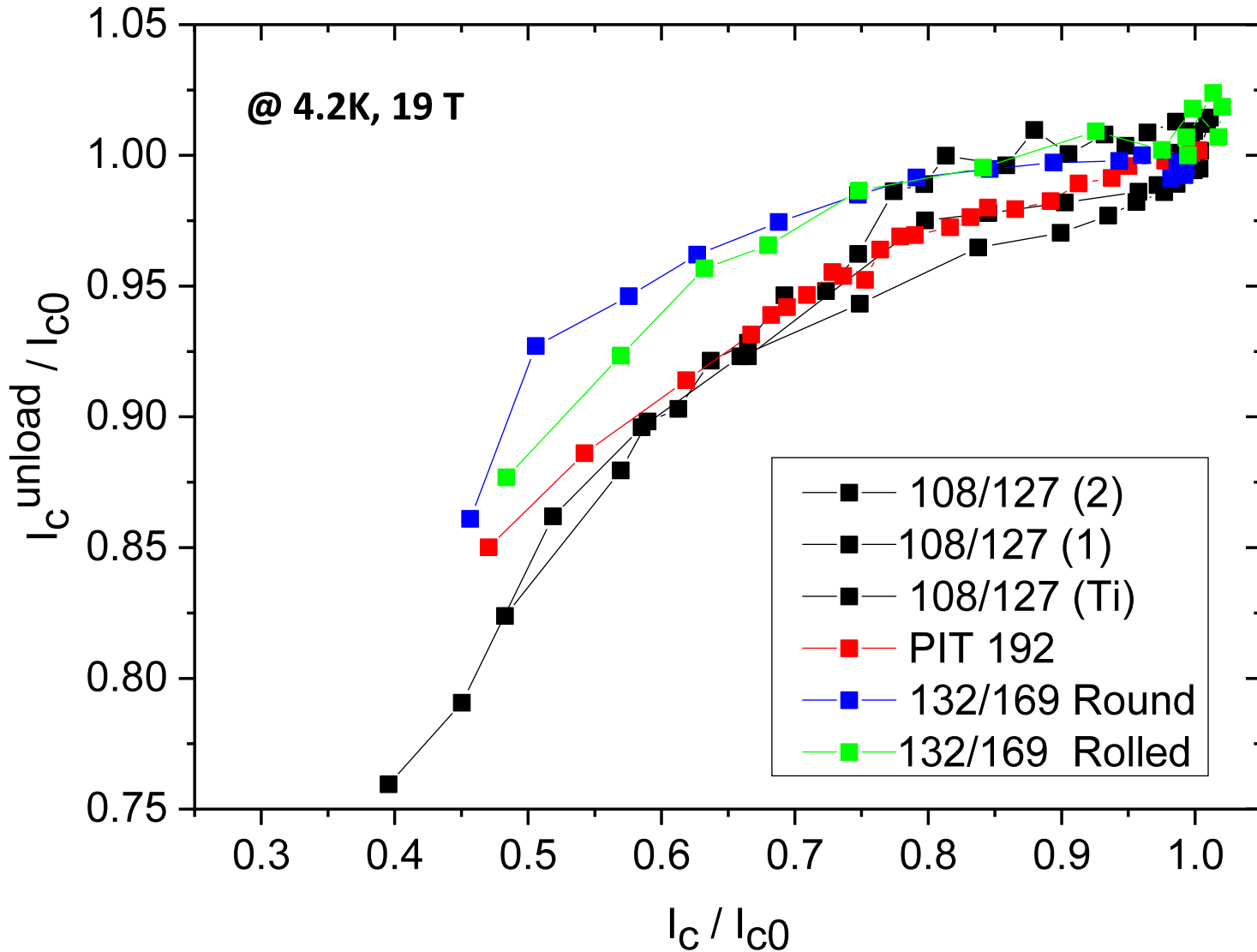


**RRP 108/127 0.85mm**



**RRP 132/169 1mm**

# *An Universal Nb<sub>3</sub>Sn curve? Not yet...*





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***Intrinsic mechanisms behind the irreversible degradation of the critical current***

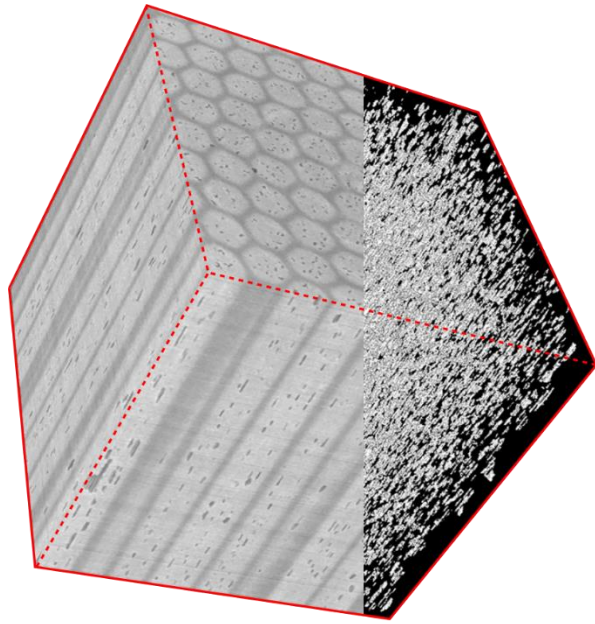


***Impact of the voids on the electromechanical properties of Nb<sub>3</sub>Sn wires.***

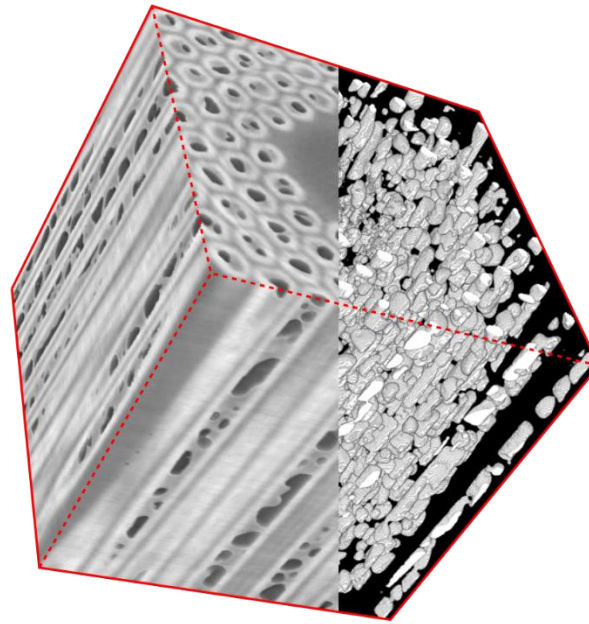
***Impact of strand layout and mechanical props.***

# *Voids in Nb<sub>3</sub>Sn wires*

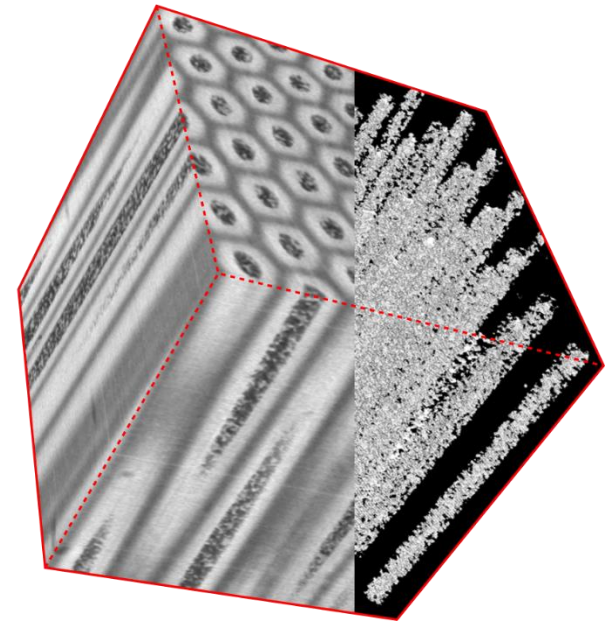
*XRD microtomography reconstruction*



***Bronze Route***  
*121 x 121 filaments*



***RRP***  
*132/169 subelements*



***PIT***  
*192 filaments*

*Can we quantify the impact of voids on the electromechanical limits?*

## *What has been done?*

*Changes in the voids correlate quantitatively with the changes in the electromechanical limits for a Bronze Route Wire*

*More details in* SCIENTIFIC REPORTS 

OPEN Quantitative correlation between the void morphology of niobium-tin wires and their irreversible critical current degradation upon mechanical loading  
C. Barth<sup>1</sup>, B. Seeber<sup>2</sup>, A. Rack<sup>3</sup>, C. Calzolaio<sup>1</sup>, Y. Zhai<sup>4</sup>, D. Matera<sup>1</sup> & C. Senatore<sup>1</sup>

<sup>1</sup>Department of Quantum Matter Physics (DQMP), University of Geneva, Geneva, Switzerland. <sup>2</sup>Department of Applied Physics (GAP), University of Geneva, Geneva, Switzerland. <sup>3</sup>European Synchrotron Radiation Facility (ESRF), Grenoble, France. <sup>4</sup>Princeton Plasma Physics Laboratory (PPPL), Princeton University, Princeton, NJ, USA. Correspondence and requests for materials should be addressed to C.B. (email: [christian.barth@unige.ch](mailto:christian.barth@unige.ch))

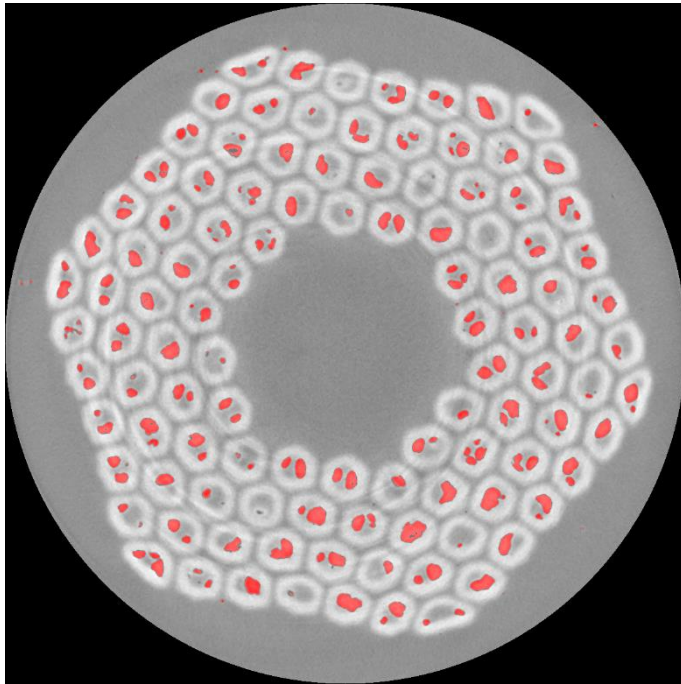
SCIENTIFIC REPORTS | (2018) 8:6589 | DOI:10.1038/s41598-018-24966-z

## *Case study on Bronze Route, what about RRP and PIT ?*

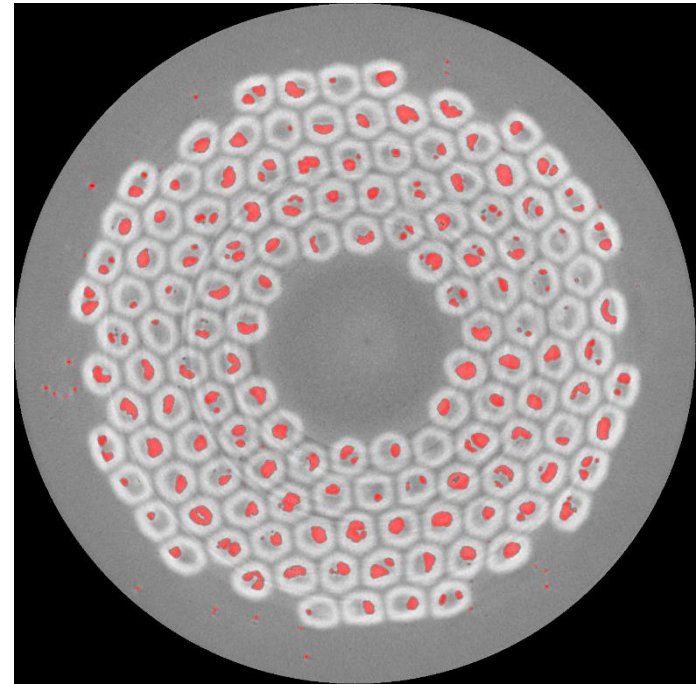
*The same approach may lead to the prediction of how much  $\varepsilon_c$  can be increased by reducing the void fraction*

## *Work on-going*

*The statistical analysis is being performed for the RRP wires:  
Size, quantity and location of voids.*



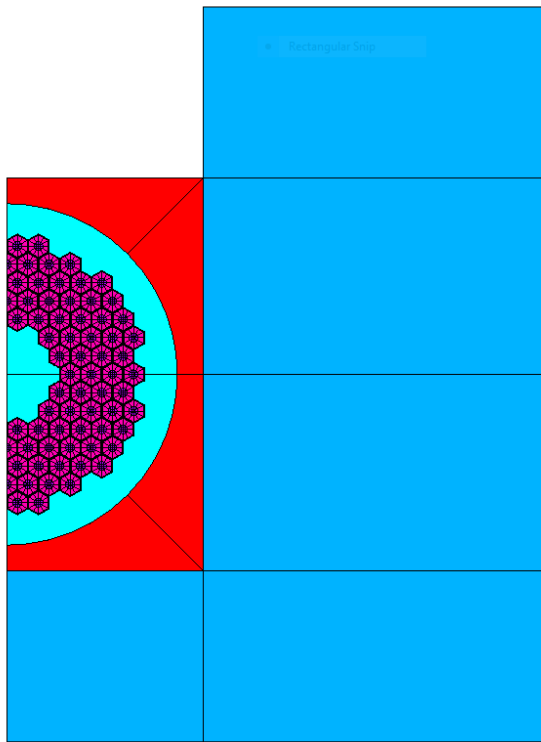
*RRP 108/127 0.85mm*



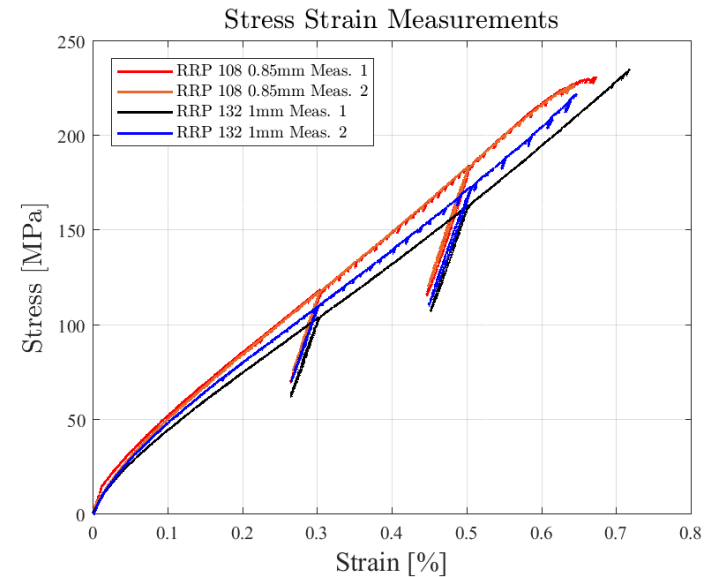
*RRP 132/169 1mm*

*Results become inputs for FEM analysis!*

# *Layout and mech. properties of $Nb_3Sn$ strands*



*FE Model*



*Tensile measurements at cold*

*Can we explain the different behavior in terms of layout, voids and mechanical properties? Investigations on-going...*

# Summary

- *An extensive campaign for electro-mechanical characterization of Nb<sub>3</sub>Sn strands is being completed.*
- *The reversible degradation and the irreversible limits for PIT and RRP strands under transversal loads are investigated.*
- *The non-negligible impact of voids needs to be considered.*
- *The study will be supported with detailed Finite Element simulations (Currently on-going).*



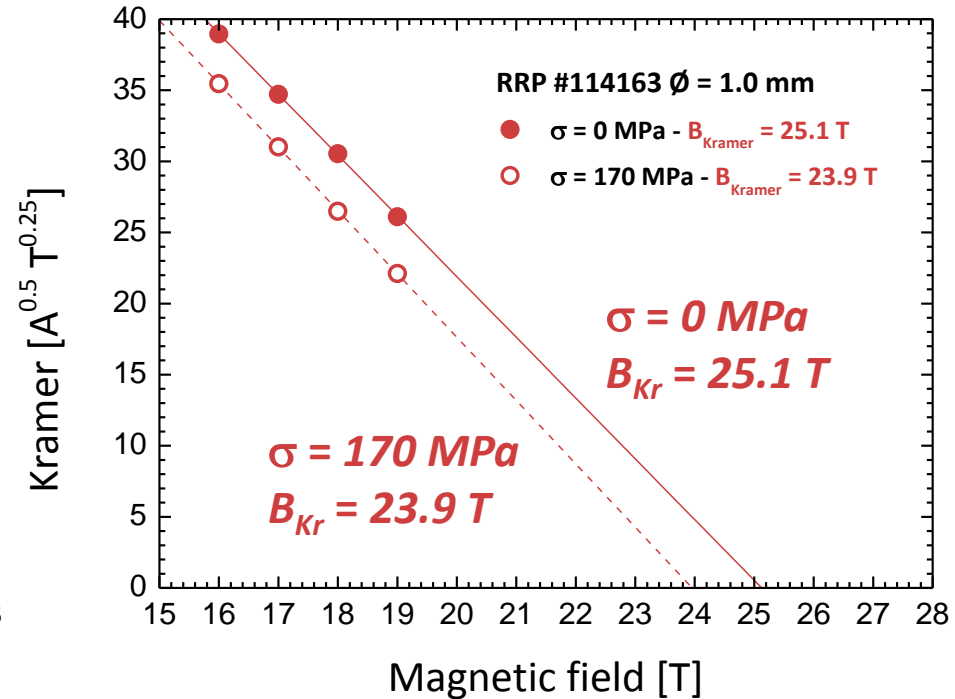
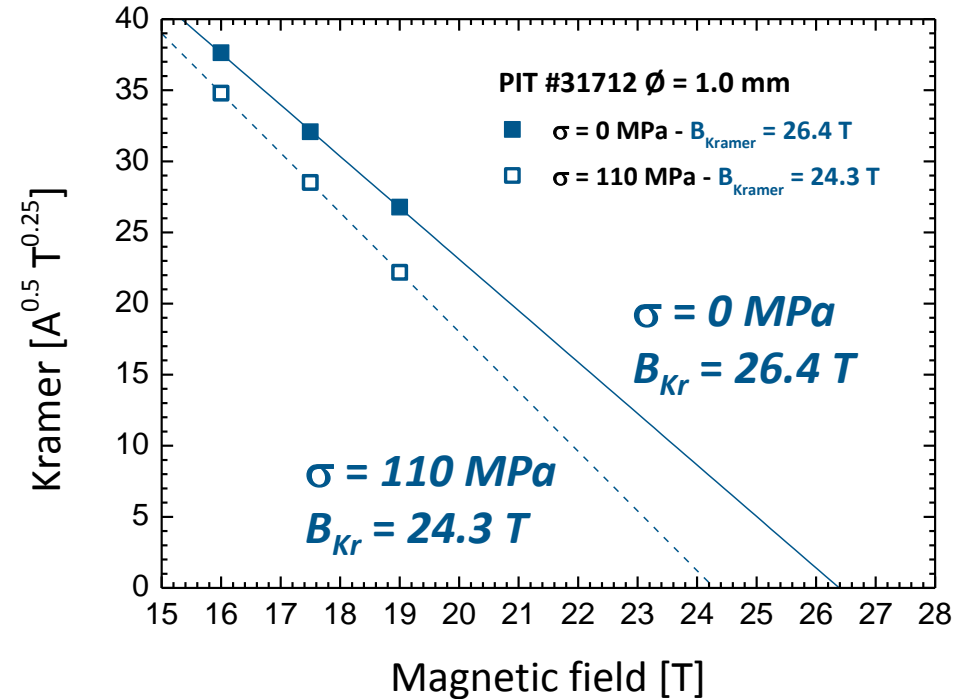
An aerial view of Paris, France, featuring the Eiffel Tower prominently on the right side. The city's dense urban landscape, including various buildings and green spaces, is visible under a soft, hazy sky. The overall tone is warm and slightly desaturated.

***Thank you for the attention !***

***<http://supra.unige.ch>***

# Kramer Plot : PIT 192 and RRP 132/169

Behind the reversible reduction of  $I_c$



The RRP wire exhibits a slower decrease of  $B_{Kr}$  with stress